

U.S.S.N. 10/791,607

In the Claims

Please cancel Claims 22,24,25,34-37 and 40.

Please amend Claim 26.

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Listing of Claims

Claims 1-25 (canceled)

26. (currently amended) A phase change memory structure comprising:

a substrate comprising a conductive area;

a spacer comprising a phase changing material sensitive to temperature and having a partially exposed sidewall region at the spacer upper portion defining a phase change memory element contact area; and

an upper conductive electrode on ~~the electrode~~ said phase change memory element contact area; wherein a spacer bottom portion partially overlaps the conductive area ~~and said upper conductive electrode at least partially overlaps said conductive area.~~

27. (original) The phase change memory structure of claim 26, wherein the upper conductive electrode comprises a material selected from the group consisting of W, TiN, TiW, TiAl, TiAlN, and combinations thereof.

28. (previously presented) A phase change memory structure comprising:

a substrate comprising a conductive area;

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a spacer having a partially exposed sidewall region at the spacer upper portion defining a phase change memory element contact area;

wherein the spacer comprises a conductive material and a spacer bottom portion partially overlaps the conductive area.

29. (original) The phase change memory structure of claim 28, wherein the conductive material comprises a material selected from the group consisting of W, TiN, TiW, TiAl, TiAlN, and combinations thereof.

30. (original) The phase change memory structure of claim 28, further comprising:

a phase changing memory element sensitive to temperature on the electrode contact area; and,

an upper conductive electrode on the phase changing memory element.

31. (original) The phase change memory structure of claim 30, wherein the phase changing memory element comprises a chalcogenide.

32. (original) The phase change memory structure of claim 31, wherein the chalcogenide comprises a material selected from

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the group consisting of Ge, Te, and Sb and their alloy system.

33. (original) The phase change memory structure of claim 30, wherein the upper conductive electrode comprises a material selected from the group consisting of W, TiN, TiW, TiAl, TiAlN, and combinations thereof.

Claims 34-40 (canceled)